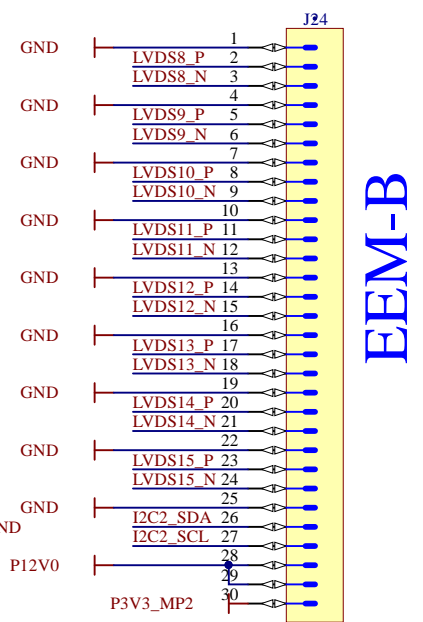
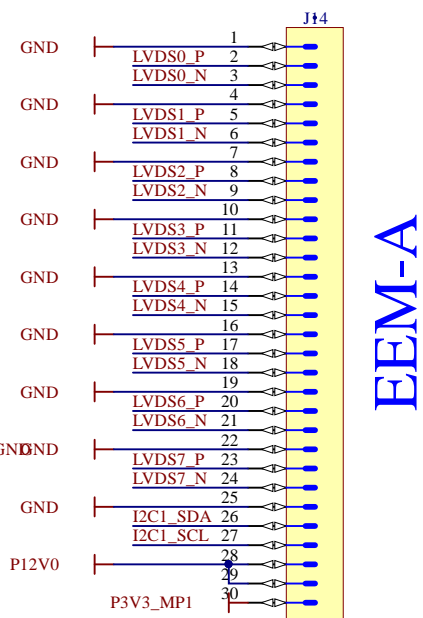
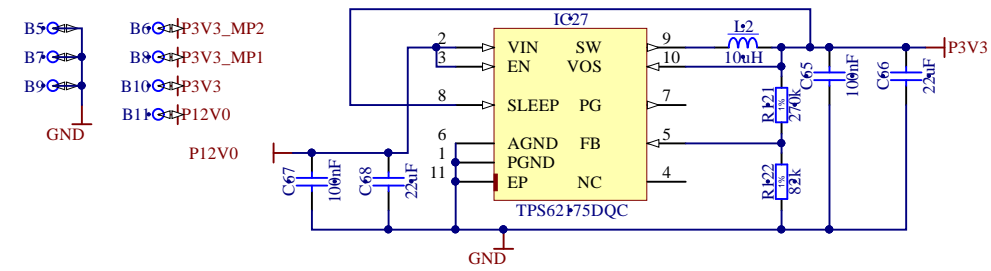
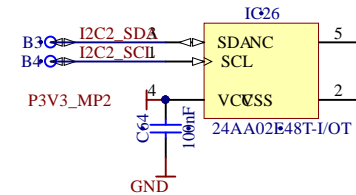
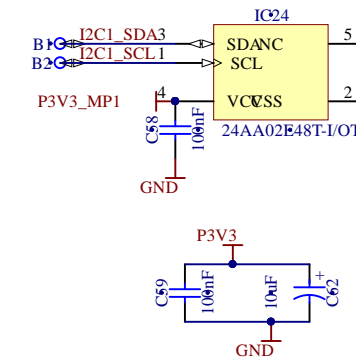
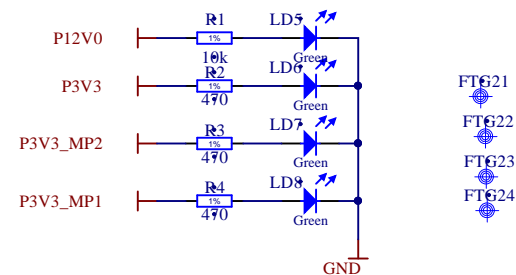
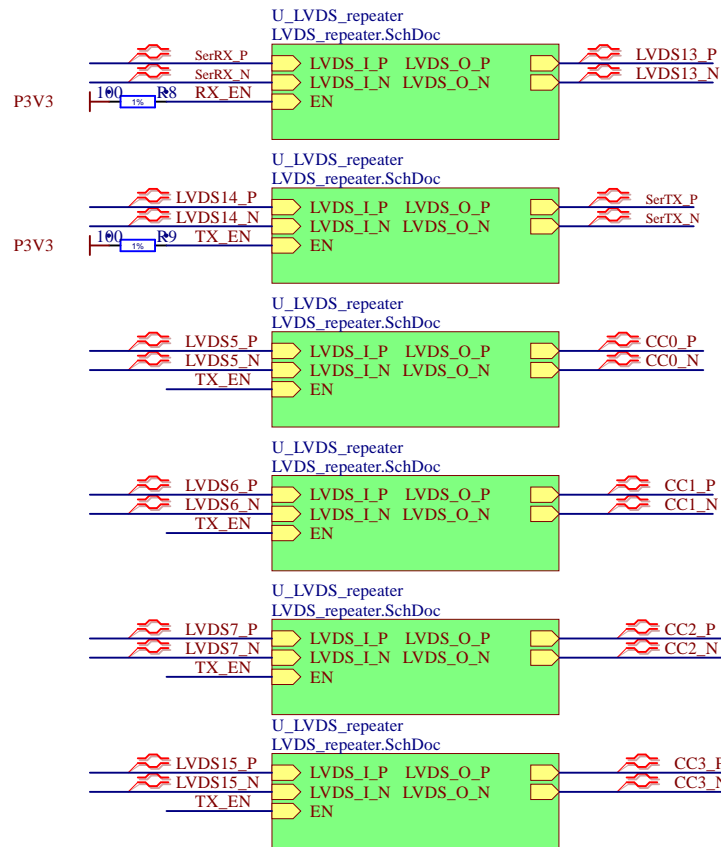
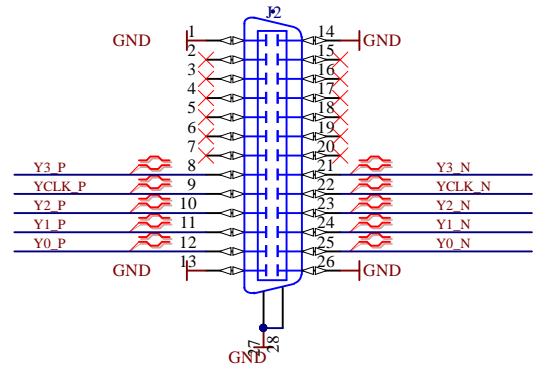


MEDIUM

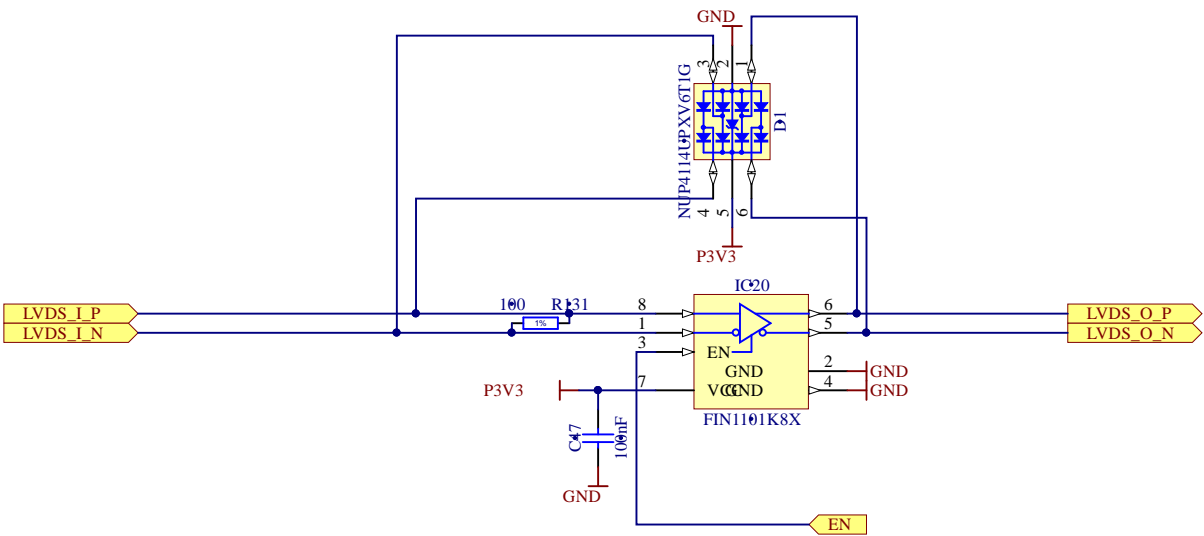


This module connects to Kasli or to VHDCI Metlino breakout board
All signals are LVDS, in case of Metlino and Kasli the VCC is 1.8V
I2C is 3.3V LVC MOS
P3V3_MP can handle up to 20mA
P12V0 rail current is up to 500mA

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Project/Equipment		KASLI 3U subsystem	
Document		Designer	G.K.
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			Rev



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Nowowiejska 15/19		ARTIQ	
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		Rev	-

PCB 3U CameraLink rev1.0

GND

KASLI CH0...7 EEM-A

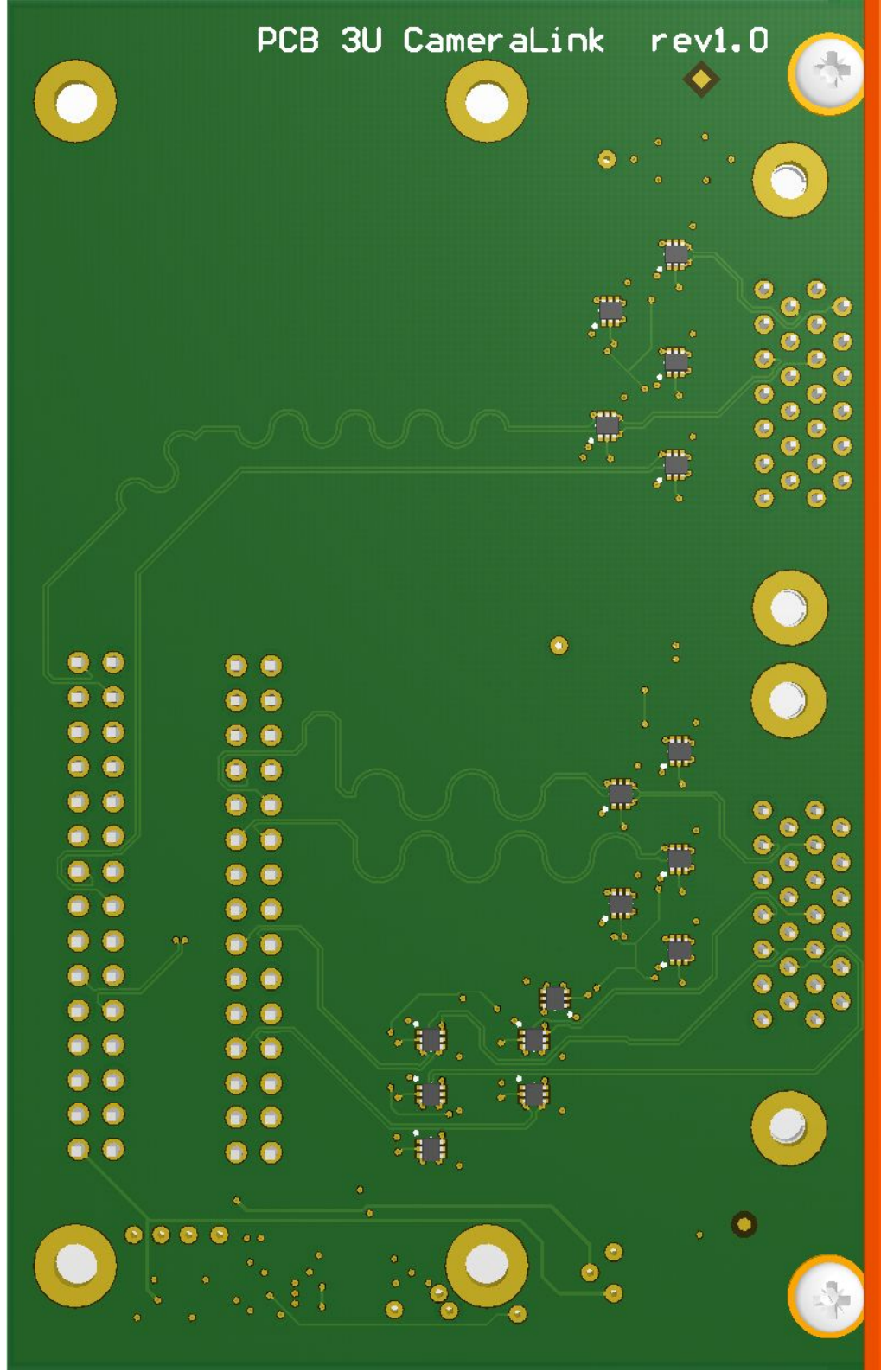
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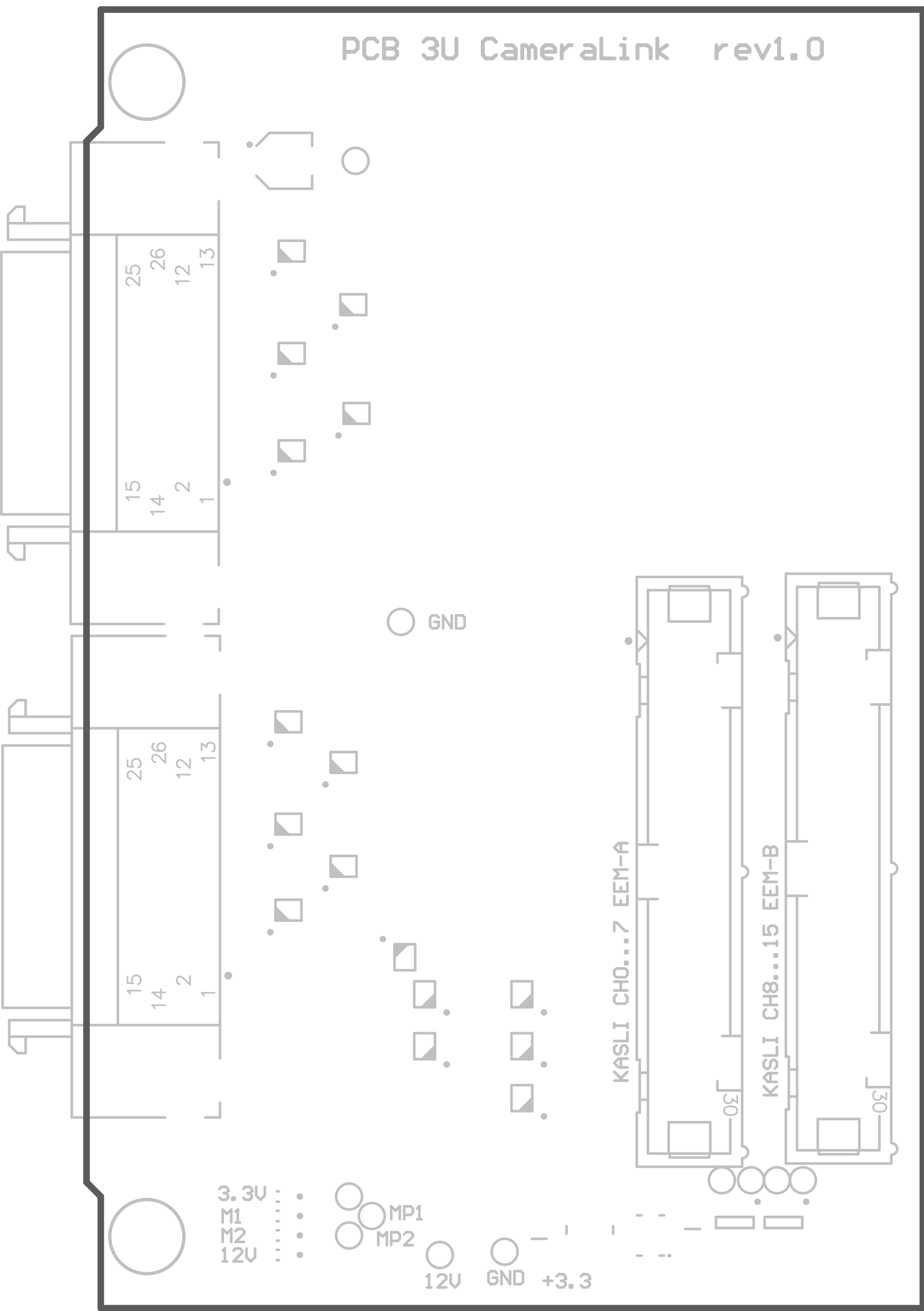
3.3V
M1
M2
12V

MP1
MP2

12V GND +3.3

PCB 3U CameraLink rev1.0





Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	TopOverlay				
2	TopSolder	Solder Resist	2.09mil	3.5	
3	TopLayer	Copper	1.40mil		
4	Dielectric1	FR-4	7.87mil	4.8	
5	Internal Plane 2	Copper	1.42mil		
6	Dielectric 4		39.37mil	4.2	
7	Internal Plane 1	Copper	1.42mil		
8	Dielectric2	FR-4	7.87mil	4.2	
9	BottomLayer	Copper	1.40mil		
10	BottomSolder	Solder Resist	2.09mil	3.5	
11	BottomOverlay				

